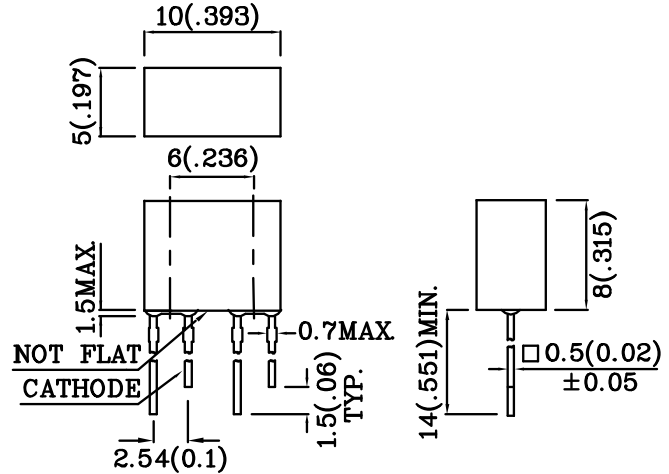




Features

- UNIFORM LIGHT EMITTING AREA.
- EASILY MOUNTED ON P.C. BOARDS OR INDUSTRY STANDARD SOCKETS.
- FLUSH MOUNTABLE.
- EXCELLENT ON/OFF CONTRAST.
- CAN BE USED WITH PANELS AND LEGEND MOUNTS.
- MECHANICALLY RUGGED.
- I.C. COMPATIBLE.
- BOTTOM SURFACE OF EPOXY IS NOT FLAT.
- RoHS COMPLIANT.



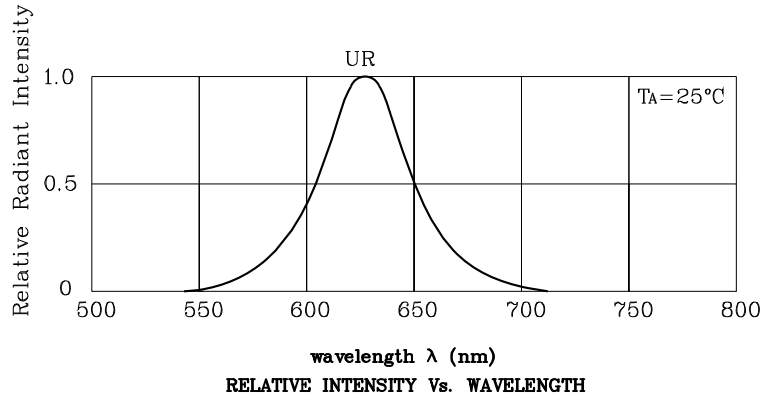
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.

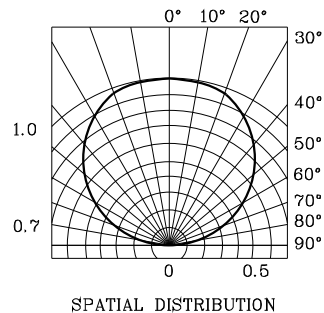
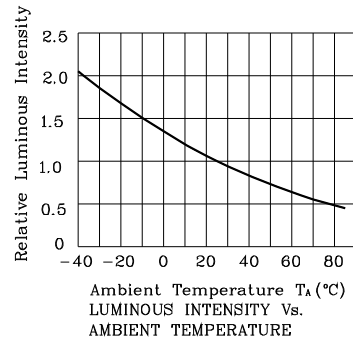
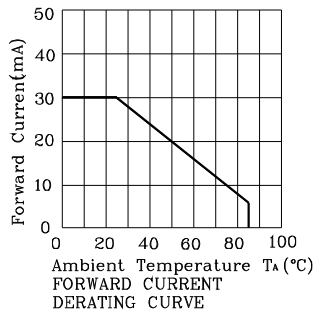
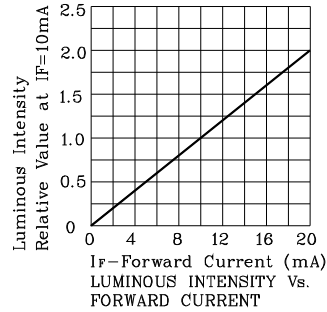
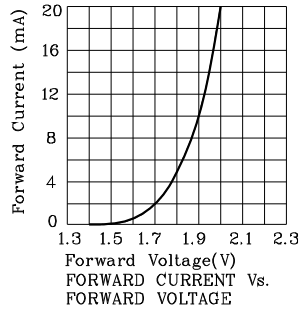
Operating Characteristics ($T_A=25^\circ\text{C}$)		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) ($I_F=10\text{mA}$)	V _F	1.9	V
Forward Voltage (Max.) ($I_F=10\text{mA}$)	V _F	2.5	V
Reverse Current(Max.) ($V_R=5\text{V}$)	I _R	10	μA
Wavelength Of Peak Emission (Typ.) ($I_F=10\text{mA}$)	λ_P	627	nm
Wavelength Of Dominant Emission (Typ.) ($I_F=10\text{mA}$)	λ_D	625	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=10\text{mA}$)	$\Delta\lambda$	45	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	pF

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		UR (GaAsP/GaP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	160	mA
Power Dissipation	P _T	75	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm below package base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm below package base]	260°C For 5 Seconds		

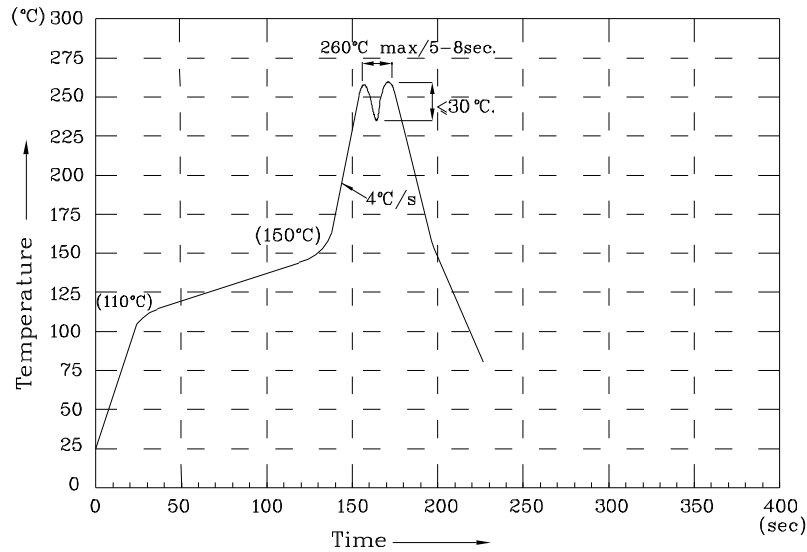
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=10\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2 θ 1/2
				min.	typ.		
EUR22D	Red	GaAsP/GaP	Red Diffused	5	9	627	120°



❖ UR



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85 degree°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.No more than once.

Remarks:

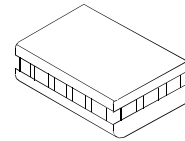
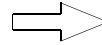
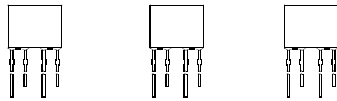
If special sorting is required (e.g. binning based on forward voltage, luminous intensity/ luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity/ Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

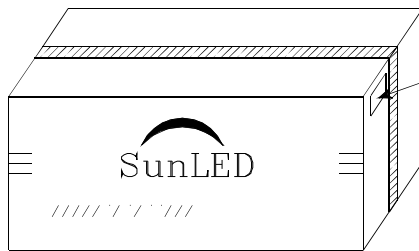
Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

EUR22D

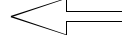


400PCS /BOARD

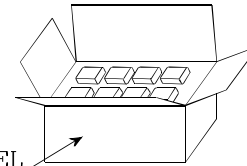


9.6K/BOX

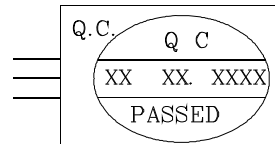
OUTSIDE LABEL




OUTSIDE LABEL



1.2K/BOX



P/NO : Exx22x	
QTY : 400 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	